



COMPAL ELECTRONICS. INC.	
PROJECT	FDI52
BOARD NO.	LA-H872P REV:1.0(A00)
LAYER NO.	SOLDEMASK_TOP
DRAW BY	Monika
Issued Date	2019-06-06
Security level	Confidential
Decipherment date	2020-06-06

Decipherment date	2020-06-06
Security level	Confidential
Issued date	2019-06-06
Drawn by	Monika
Layer no.	SOLDERMASK_BOTTOM
Board no.	LA-H875P REV:1.0(A00)
Project	FDI25
COMPAL ELECTRONICS, INC.	

